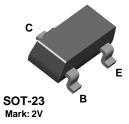


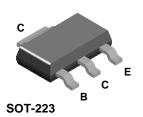
MPSA64

MMBTA64

PZTA64







PNP Darlington Transistor

This device is designed for applications requiring extremely high current gain at currents to 800 mA. Sourced from Process 61.

Absolute Maximum Ratings* TA = 25°C unless otherwise noted

| Symbol | Parameter | Value | Units |
|-----------------------------------|--|-------------|-------|
| V _{CES} | Collector-Emitter Voltage | 30 | V |
| V _{CBO} | Collector-Base Voltage | 30 | V |
| V _{EBO} | Emitter-Base Voltage | 10 | V |
| I _C | Collector Current - Continuous | 1.2 | A |
| T _J , T _{stg} | Operating and Storage Junction Temperature Range | -55 to +150 | °C |

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

 3) All voltages (V) and currents (A) are negative polarity for PNP transistors.

Thermal Characteristics TA = 25°C unless otherwise noted

| Symbol | Characteristic Max | | | | | |
|-----------------|---|--------|----------|----------|-------|--|
| | | MPSA64 | *MMBTA64 | **PZTA64 | | |
| P_{D} | Total Device Dissipation | 625 | 350 | 1,000 | mW | |
| | Derate above 25°C | 5.0 | 2.8 | 8.0 | mW/°C | |
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case | 83.3 | | | °C/W | |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | 200 | 357 | 125 | °C/W | |

^{*}Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

^{**}Device mounted on FR-4 PCB 36 mm X 18 mm X 1.5 mm; mounting pad for the collector lead min. $6 \, \text{cm}^2$.

PNP Darlington Transistor

(continued)

Electrical Characteristics

TA = 25°C unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Max | Units | | | | |
|----------------------|-------------------------------------|------------------------------------|-----|-----|-------|--|--|--|--|
| OFF CHARACTERISTICS | | | | | | | | | |
| V _{(BR)CES} | Collector-Emitter Breakdown Voltage | $I_C = 100 \mu A, I_B = 0$ | 30 | | V | | | | |
| I _{CBO} | Collector-Cutoff Current | $V_{CB} = 30 \text{ V}, I_{E} = 0$ | | 100 | nA | | | | |
| I _{EBO} | Emitter-Cutoff Current | $V_{EB} = 10 \text{ V}, I_{C} = 0$ | | 100 | nA | | | | |

ON CHARACTERISTICS*

| h _{FE} | DC Current Gain | $I_C = 10 \text{ mA}, V_{CE} = 5.0 \text{ V}$ | 10,000 | | |
|----------------------|--------------------------------------|--|--------|-----|---|
| | | $I_C = 100 \text{ mA}, V_{CE} = 5.0 \text{ V}$ | 20,000 | | |
| V _{CE(sat)} | Collector-Emitter Saturation Voltage | $I_C = 100 \text{ mA}, I_B = 0.1 \text{ mA}$ | | 1.5 | V |
| V _{BE(on)} | Base-Emitter On Voltage | $I_C = 100 \text{ mA}, V_{CE} = 5.0 \text{ V}$ | | 2.0 | V |

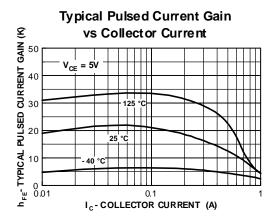
SMALL SIGNAL CHARACTERISTICS

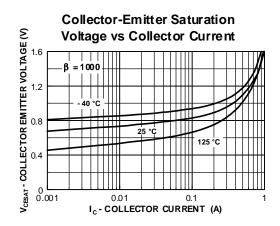
| f _T | Current Gain - Bandwidth Product | $I_C = 10 \text{ mA}, V_{CE} = 5.0 \text{ V},$ | 125 | MHz |
|----------------|----------------------------------|--|-----|-----|
| | | f = 100 MHz | | |

^{*}Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

NOTE: All voltages (V) and currents (A) are negative polarity for PNP transistors.

Typical Characteristics



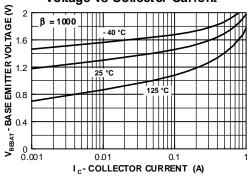


PNP Darlington Transistor

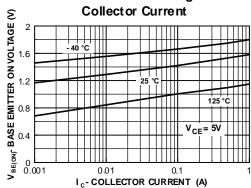
(continued)

Typical Characteristics (continued)

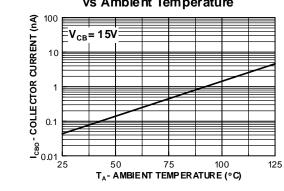




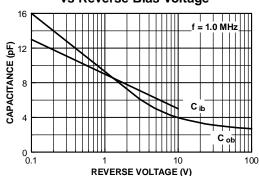
Base Emitter ON Voltage vs



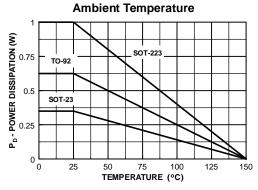
Collector-Cutoff Current vs Ambient Temperature



Input and Output Capacitance vs Reverse Bias Voltage



Power Dissipation vs

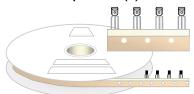


TO-92 Tape and Reel Data FAIRCHILD SEMICONDUCTOR TM **TO-92 Packaging** Configuration: Figure 1.0 **TAPE and REEL OPTION** FSCINT Label sample See Fig 2.0 for various Reeling Styles CBVK//418019 **FSCINT** Label 5 Reels per Intermediate Box Customized F63TNR Label sample Label F63TNR LOT: CBVK741B019 QTY: 2000 FSID: PN222N Customized QTY1: QTY2: 375mm x 267mm x 375mm Intermediate Box TO-92 TNR/AMMO PACKING INFROMATION **AMMO PACK OPTION** See Fig 3.0 for 2 Ammo Packing Style Quantity EOL code **Pack Options** 2,000 D26Z Е 2,000 D27Z Ammo М 2,000 D74Z 2,000 D75Z **FSCINT** Unit weight = 0.22 gm Reel weight with components = 1.04 kg Ammo weight with components = 1.02 kg Max quantity per intermediate box = 10,000 units Label 5 Ammo boxes per Intermediate Box 327mm x 158mm x 135mm Immediate Box Customized F63TNR Customized Label Label 333mm x 231mm x 183mm Intermediate Box (TO-92) BULK PACKING INFORMATION **BULK OPTION** See Bulk Packing DESCRIPTION QUANTITY Information table J18Z TO-18 OPTION STD 2.0 K / BOX Anti-static Bubble Sheets TO-5 OPTION STD 1.5 K / BOX NO LEAD CLIP J05Z FSCINT Label NO EOL TO-92 STANDARD STRAIGHT FOR: PKG 92, NO LEADCLIP 2.0 K / BOX 94 (NON PROELECTRON SERIES), 96 TO-92 STANDARD STRAIGHT FOR: PKG 94 (PROELECTRON SERIES BCXXX, BFXXX, BSRXXX), 97, 98 L34Z NO LEADCLIP 2.0 K / BOX 2000 units per 114mm x 102mm x 51mm EO70 box for std option Immediate Box 5 EO70 boxes per intermediate Box 530mm x 130mm x 83mm Customized Intermediate box Label FSCINT Label 10,000 units maximum per intermediate box for std option

TO-92 Tape and Reel Data, continued

TO-92 Reeling Style Configuration: Figure 2.0

Machine Option "A" (H)

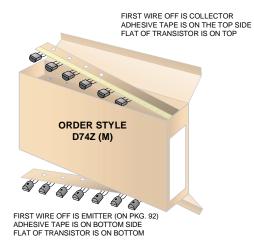


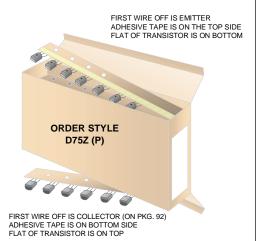
Style "A", D26Z, D70Z (s/h)

Machine Option "E" (J)

Style "E", D27Z, D71Z (s/h)

TO-92 Radial Ammo Packaging Configuration: Figure 3.0





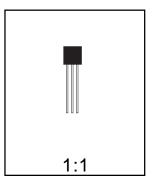
TO-92 Tape and Reel Data, continued **TO-92 Tape and Reel Taping Dimension Configuration:** Figure 4.0 ₽2 ITEM DESCRIPTION SYMBOL DIMENSION Base of Package to Lead Bend 0.098 (max) 0.928 (+/- 0.025) Component Height Ha **User Direction of Feed** Lead Clinch Height HO 0.630 (+/- 0.020) 0.748 (+/- 0.020) Component Base Height H1 Component Alignment (side/side) 0.040 (max) Component Alignment (front/back) Hd 0.031 (max) Component Pitch 0.500 (+/- 0.020) РО 0.500 (+/- 0.008) Feed Hole Pitch Hole Center to First Lead 0.150 (+0.009, -0.010) P2 0.247 (+/- 0.007) Hole Center to Component Center Lead Spread F1/F2 0.104 (+/- 0 .010) Lead Thickness d 0.018 (+0.002, -0.003) Cut Lead Length 0.429 (max) Taped Lead Length 0.209 (+0.051, -0.052) Taped Lead Thickness 0.032 (+/- 0.006) 0.021 (+/- 0.006) Carrier Tape Thickness Carrier Tape Width 0.708 (+0.020, -0.019) TO-92 Reel Hold - down Tape Width WO 0.236 (+/- 0.012) Configuration: Figure 5.0 0.035 (max) Hold - down Tape position W1 0.360 (+/- 0.025) Feed Hole Position W2 Sprocket Hole Diameter DO 0.157 (+0.008, -0.007) Lead Spring Out 0.004 (max) Note: All dimensions are in inches D4 ITEM DESCRIPTION SYSMBOL MINIMUM MAXIMUM Reel Diameter 13.975 14.025 F63TN Arbor Hole Diameter (Standard) 1.160 1.200 0.650 0.700 3.100 3.300 3.100 Hub Recess Inner Diameter 2.700 W1 0.570 0.370 Hub Recess Depth Flange to Flange Inner Width W2 1.690 1.630 Hub to Hub Center Width WЗ 2.090 Note: All dimensions are inches

TO-92 Package Dimensions



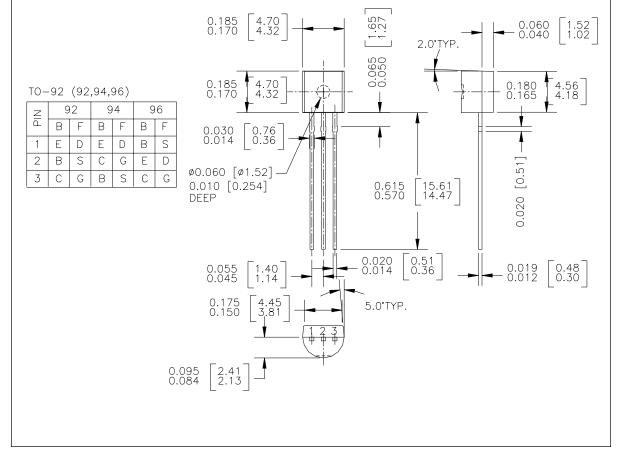
TO-92 (FS PKG Code 92, 94, 96)

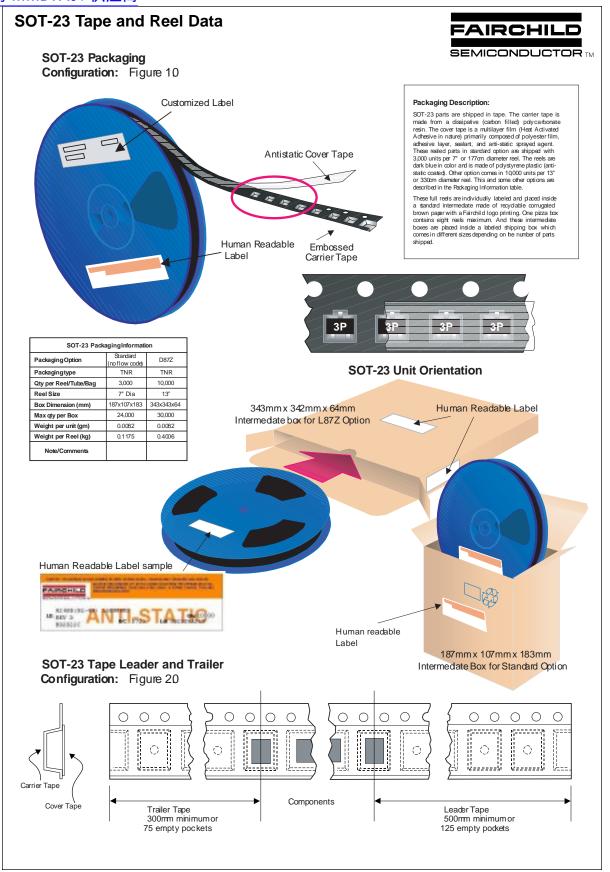




Scale 1:1 on letter size paper
Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.1977

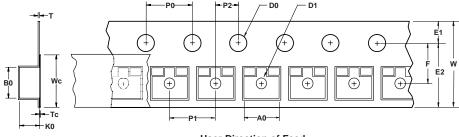




SOT-23 Tape and Reel Data, continued

SOT-23 Embossed Carrier Tape

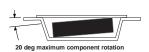
Configuration: Figure 3.0



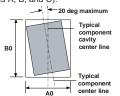
User Direction of Feed

| | Dimensions are in millimeter | | | | | | | | | | | | | |
|---------------------|------------------------------|-----------------|---------------|-----------------|-------------------|-----------------|-------------|-----------------|---------------|---------------|-----------------|-------------------|---------------|-----------------|
| Pkg type | Α0 | В0 | w | D0 | D1 | E1 | E2 | F | P1 | P0 | K0 | Т | Wc | Тс |
| SOT-23 (8mm) | 3.15 +/-0.10 | 2.77 +/-0.10 | 8.0 +/-0.3 | 1.55 +/-0.05 | 1.125 +/-0.125 | 1.75 +/-0.10 | 6.25 min | 3.50 +/-0.05 | 4.0 +/-0.1 | 4.0 +/-0.1 | 1.30 +/-0.10 | 0.228 +/-0.013 | 5.2 +/-0.3 | 0.06 +/-0.02 |

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation



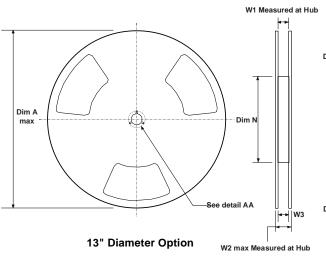
Sketch B (Top View)
Component Rotation

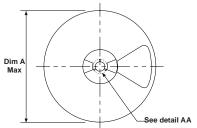


Sketch C (Top View)

Component lateral movement

SOT-23 Reel Configuration: Figure 4.0





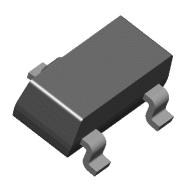
7" Diameter Option B Min Dim C Dim C DETAIL AA

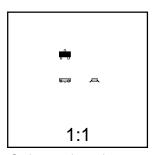
| | Dimensions are in inches and millimeters | | | | | | | | |
|-----------|--|---------------|--------------|-----------------------------------|---------------|-------------|-----------------------------------|---------------|-----------------------------|
| Tape Size | Reel Option | Dim A | Dim B | Dim C | Dim D | Dim N | Dim W1 | Dim W2 | Dim W3 (LSL-USL) |
| 8mm | 7" Dia | 7.00 177.8 | 0.059 1.5 | 512 +0.020/-0.008 13 +0.5/-0.2 | 0.795 20.2 | 2.165 55 | 0.331 +0.059/-0.000 8.4 +1.5/0 | 0.567 14.4 | 0.311 - 0.429 7.9 - 10.9 |
| 8mm | 13" Dia | 13.00 330 | 0.059 1.5 | 512 +0.020/-0.008 13 +0.5/-0.2 | 0.795 20.2 | 4.00 100 | 0.331 +0.059/-0.000 8.4 +1.5/0 | 0.567 14.4 | 0.311 - 0.429 7.9 - 10.9 |

SOT-23 Package Dimensions



SOT-23 (FS PKG Code 49)

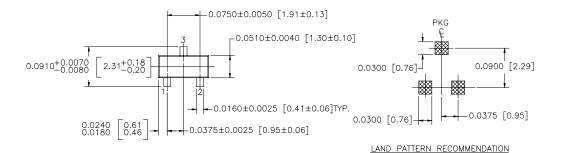


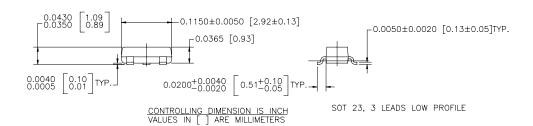


Scale 1:1 on letter size paper

Dimensions shown below are in: inches [millimeters]

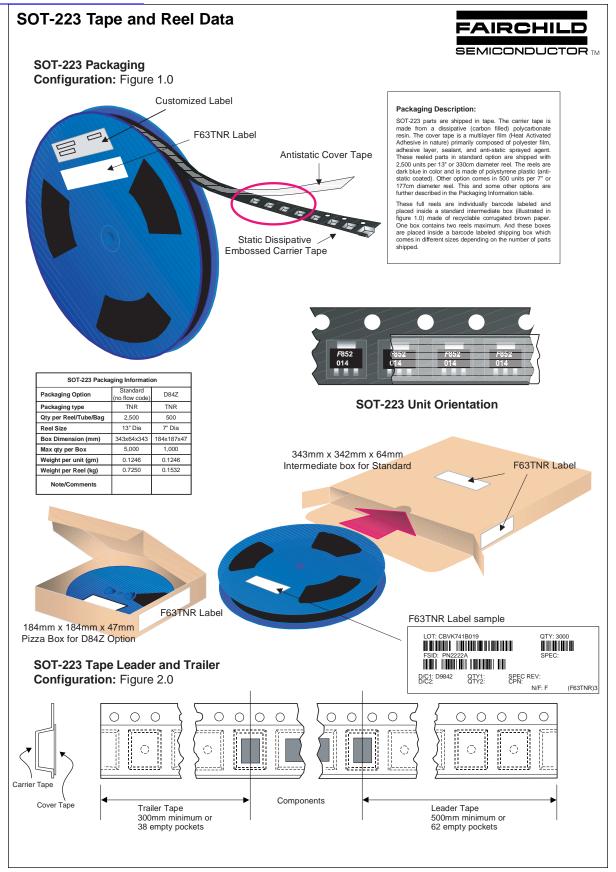
Part Weight per unit (gram): 0.0082





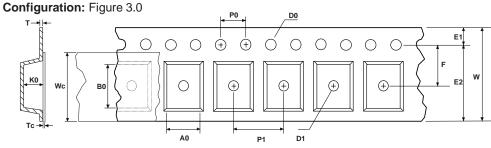
NOTE: UNLESS OTHERWISE SPECIFIED

- 1. STANDARD LEAD FINISH 150 MICROINCHES / 3.81 MICROMETERS MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42
- 2. REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE G, DATED JUL 1993



SOT-223 Tape and Reel Data, continued

SOT-223 Embossed Carrier Tape



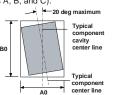
| U | ser Direction of Feed | |
|---|-----------------------|---|
| | | _ |

| | Dimensions are in millimeter | | | | | | | | | | | | | |
|-----------------------|------------------------------|-----------------|----------------|-----------------|-----------------|-----------------|--------------|-----------------|---------------|---------------|-----------------|------------------------|-----------------|-----------------|
| Pkg type | Α0 | В0 | w | D0 | D1 | E1 | E2 | F | P1 | P0 | K0 | Т | Wc | Тс |
| SOT-223 (12mm) | 6.83 +/-0.10 | 7.42 +/-0.10 | 12.0 +/-0.3 | 1.55 +/-0.05 | 1.50 +/-0.10 | 1.75 +/-0.10 | 10.25 min | 5.50 +/-0.05 | 8.0 +/-0.1 | 4.0 +/-0.1 | 1.88 +/-0.10 | 0.292 +/- 0.0130 | 9.5 +/-0.025 | 0.06 +/-0.02 |

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



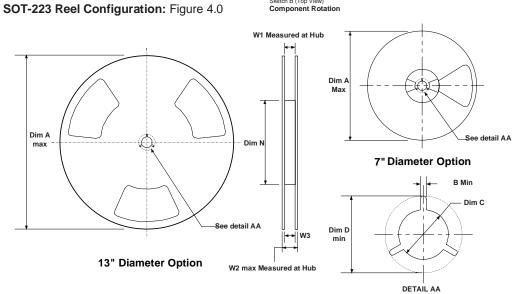
Sketch A (Side or Front Sectional View)
Component Rotation



Sketch B (Top View)
Component Rotation



Sketch C (Top View)
Component lateral movement

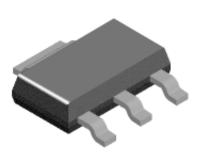


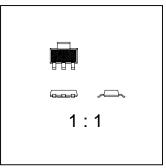
| | Dimensions are in inches and millimeters | | | | | | | | |
|-----------|--|---------------|--------------|-----------------------------------|---------------|--------------|----------------------------------|---------------|------------------------------|
| Tape Size | Reel Option | Dim A | Dim B | Dim C | Dim D | Dim N | Dim W1 | Dim W2 | Dim W3 (LSL-USL) |
| 12mm | 7" Dia | 7.00 177.8 | 0.059 1.5 | 512 +0.020/-0.008 13 +0.5/-0.2 | 0.795 20.2 | 5.906 150 | 0.488 +0.078/-0.000 12.4 +2/0 | 0.724 18.4 | 0.469 - 0.606 11.9 - 15.4 |
| 12mm | 13" Dia | 13.00 330 | 0.059 1.5 | 512 +0.020/-0.008 13 +0.5/-0.2 | 0.795 20.2 | 7.00 178 | 0.488 +0.078/-0.000 12.4 +2/0 | 0.724 18.4 | 0.469 - 0.606 11.9 - 15.4 |

SOT-223 Package Dimensions



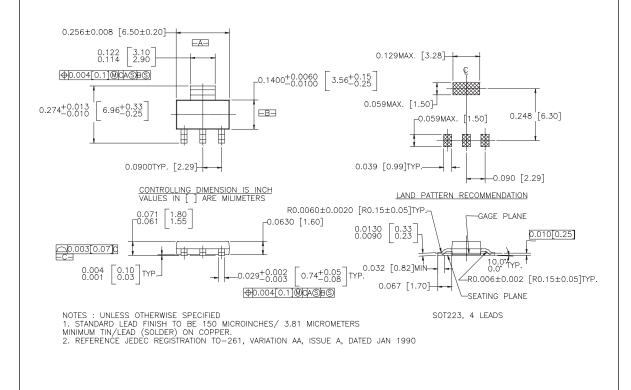
SOT-223 (FS PKG Code 47)





Scale 1:1 on letter size paper

Part Weight per unit (gram): 0.1246



查询"MMBTA64"供应商

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

 $ACEx^{TM}$ FASTr™ PowerTrench® SyncFET™ QFET™ TinyLogic™ Bottomless™ GlobalOptoisolator™ UHC™ QSTM CoolFET™ **GTO™ VCX**TM $CROSSVOLT^{\mathsf{TM}}$ QT Optoelectronics™ HiSeC™

DOME™ ISOPLANAR™ Quiet Series™

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

| Datasheet Identification | Product Status | Definition |
|--------------------------|---------------------------|---|
| Advance Information | Formative or In Design | This datasheet contains the design specifications for product development. Specifications may change in any manner without notice. |
| Preliminary | First Production | This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design. |
| No Identification Needed | Full Production | This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design. |
| Obsolete | Not In Production | This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only. |